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APR 2 0 2001
PATENT & TRADEMARK OFFICE

GAU 3.723

Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800 Group Art Unit: 3723

Filed: September 28, 2000 Examiner: Not Yet Assigned

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE AND LAYER STRUCTURE MADE THEREBY

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ADDITIONAL CLAIMS FEE CHART

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TECHNOLOGY CENTER R3700
3700 MAIL ROOM

Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith is a Second Preliminary Amendment for filing and the filing fee is calculated below:

For	No. After Amendment		Highest No. Prev. Filed		No. Extra		Rate	Fee
Total Claims	61	-	38	=	23	x	$ 9/$18	= $414
Indep. Claims	5	-	3	=	2	x	$40/$80	= $160
Multiple Dependent Claim Presented							$135/$270	=$270
							TOTAL:	$844

XX Two checks in the amount of $844.00 are enclosed.

XX The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 05-1323 (Docket #2022/48819). A duplicate copy of this sheet is attached.

Respectfully submitted,

April 20, 2001

Richard R. Diefendorf
Registration No. 32,390

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L. Nelson
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PATENT

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SECOND PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please add the following new claims prior to examination:

B1

--39. A process for forming a conductive material structure on a surface of a substrate, wherein the surface of the substrate includes a top portion and cavity portions, the process comprising the steps of:

applying an electrolyte solution to the surface of the substrate while applying a first potential to the substrate so as to deposit a planar layer of a conductive material out of the electrolyte solution onto the surface including the top portion and into the cavity portions; and

reducing the thickness of the planar layer in a planar manner while continuing to apply the electrolyte solution to the surface of the substrate.

40. The process of Claim 39, wherein the step of reducing the thickness of the planar layer comprises applying a

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